



brewer science

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BrewerBOND[®] 530

Temporary wafer bonding release material for mechanical debonding applications

BENEFITS

- Compatible with 250°C - 300°C bonding materials
- Simple application on carrier substrate
- Lower cost of ownership with carrier substrate reuse
- Carrier substrate rework by solvent clean, RCA clean, or ash
- Low-force separation

MATERIAL PROPERTIES

Viscosity (Dynamic): 12.4 cPs at 25°C (77°F)

WARNING: The maximum process temperature of BrewerBOND[®] 530 release material is 300°C. Do not process this material above 300°C for any reason. Please refer to the safety data sheet (SDS) for more information.

PROCESSING

Coating Guidelines

Static dispense in center of wafer

Spin coat: 1000 to 2000 rpm* for 30 s

Acceleration: 3000 rpm/s

Contact bake (hot plate): 200°C for 2 min

* Spin speed of ≥ 1500 rpm is recommended based on Brewer Science best known method (BKM). See spin speed curve for target thickness.

Spin Speed Curve

